Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

6545b/Tag 15.6"

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries battery and RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 screw driver</td>
<td>philip #1 / TORX T8</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Battery module
2. Remove Mini card door
3. Remove Ram door.
4. Remove Blue tooth door.
5. Remove HDD door.
6. Remove HDD module
7. Remove ODD assembly
8. Remove Keyboard
9. Remove strip cover (with power button PCB & caps lock PCB)
10. Remove LCD cable and antenna connector
11. Divide LCD assembly from base assembly
12. Remove palm rest sub-assembly
13. Remove TP module & RTC battery
14. Divide logic-up assembly(w/buttons) from base assembly
15. Divide small PCB from base assembly
16. Remove speaker
17. Remove fan module
18. Divide MB from base assembly
19. Divide RS232 PCB & RJ11 from lower sub-assy
20. Divide thermal module & ODD trans PCB
21. Divide LCD cover & LCD bezel.
22. Divide LCD panel and Hinge Bracket.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Step 1. Remove Battery module

Step 2. Remove Mini card door.

Step 3. Remove Ram door.

Step 4. Remove Blue tooth door.

Step 5. Remove HDD door.

Step 6. Remove HDD module.
Step 7. Remove ODD assembly

Step 8. Remove Keyboard

Step 9. Remove strip cover

Step 10-11. Remove LCD cable and antenna connector. Divide LCD assembly from base assembly
Step 12. Remove palm rest sub-assembly

Step 13. Remove TP module & RTC battery

Step 14. Divide logic-up assembly (w/buttons) from base assembly

Step 15. Divide small PCB from base assembly

Step 16. Remove speaker.

Step 17. Remove fan module
Step 18. Divide MB (w/thermal module) from base assembly  
Step 19. Divide RS232 PCB & RJ11 from lower sub-assy

Step 20. Divide thermal module & ODD trans PCB

Step 21-22. Divide LCD cover & LCD bezel. Divide LCD panel and Hinge Bracket.